



Minutes of Administrative Chapter Meeting 2013

Date/Time: September 30, 2012, 16:00 hrs.
Location: Sensirion AG, Stäfa

Attendees

Hamit Duran (ABB, Chapter Chair)
Daniel Thommen (Microdul, Vice Chair)
Rony Jose James (CSEM, Treasurer)
Slavo Kicin (ABB, Program Officer and Webmaster)
Werner Hunziker (Sensirion)
Michael Schumacher (Enics)
Christian Bosshard (CSEM)
Wolfram Teppan (LEM SA)
Farzad Parsaie Nasab
Franziska Brem (ABB)
Eduardo Jr. Baruelo (Semtech)
Rene Zingg (Zinan Technologies GmbH)
Stefan Weiss (Oclaro)

Guests

Hugo Wyss (Chair, LM-Group IEEE Switzerland)
Samuel Hartmann (ABB)
Martin Herrmann (Microdul)
David Barbagallo (LEM SA)
Anwar Hashmi (Phonak)
Harry Rudin
Marc von Waldkirch (Sensirion)
Stephan Braun (Sensirion)
Ian Kilburn (Phonak)

Technical Part

A general introduction to Sensirion was given by Marc von Waldkirch followed by a company tour led by Werner Hunziker and Stephan Braun.

Administrative Part

Chapter report presented by Hamit Duran

- Information about the chapter board and the membership status: 52 (annual leave 6)
The board meets monthly via telco
- General overview on IEEE benefits was given
- Report about the 2012 activity of the CPMT Switzerland Chapter
 - Visit and general assembly at Microdul Switzerland AG, Zurich on October 25, 2012
 - Seminar on reliability of electronic components & systems at EMPA Duebendorf on June 24, 2013
(see <http://www.ieee.ch/assets/Uploads/CPMT/CPMTEMPA2013Reliability-seminar-program-Final.pdf>)
- Review/Outlook on Main IEEE CPMT Conferences in 2013/2014
- Financial report (balance as of 31.12.2012): CHF 100.50
- Outlook 2014:
 - Possible topics for seminars/talks in 2014:
3D packaging, Biomedical packaging, Microwave/RF packaging
 - Joint event with IEEE CPMT chapter in neighboring countries (Germany, Austria, France, Italy)?

Social Part

An apéro was offered by Sensirion AG after the administrative part. A common dinner in Stäfa (at own expenses) concluded this event.

October 22, 2013

Daniel Thommen
Chapter Vice Chair